

C1 would
a belt forming a closed loop; and
at least one polishing pad mounted on the belt;
wherein said belt is formed of metal.

C2
SUB D2
34. (Amended) A polishing pad assembly for polishing a semiconductor wafer, said assembly comprising:
a first roller;
at least one additional roller;
a belt forming a closed loop, which belt is mounted on said first roller and said at least one additional roller;
at least one polishing pad mounted to said belt; and
a drive system coupled to at least said first roller to rotate said first roller and to cause said belt and said polishing pad to move in a path;
wherein said belt is formed of metal.

C3
--36. (New) A polishing pad assembly for polishing a semiconductor wafer, said assembly comprising:
a belt forming a closed loop; and
at least one polishing pad mounted on the belt;
wherein the polishing pad comprises a polyurethane material.--

SUB D3
--37. (New) A polishing pad assembly for polishing a semiconductor wafer, said assembly comprising:
a first roller;
at least one additional roller;
a belt forming a closed loop, which belt is mounted on said first roller and said at least one additional roller;
at least one polishing pad mounted to said belt; and
a drive system coupled to at least said first roller to rotate said first roller and to cause said belt and said polishing pad to move in a path;
wherein the polishing pad comprises a polyurethane material.--

--38. (New) A polishing pad assembly for polishing a semiconductor wafer,
said assembly comprising:

a belt forming a closed loop; and
at least one polishing pad mounted on the belt;
wherein the belt comprises a high-strength polymer.--

8 --39. (New) The invention of Claim 38 wherein the belt comprises a
polyethylene terephthalate resin.--

Sub D4
C3
cancel
--40. (New) A polishing pad assembly for polishing a semiconductor wafer,
said assembly comprising:

a first roller;
at least one additional roller,
a belt forming a closed loop, which belt is mounted on said first roller and
said at least one additional roller;
at least one polishing pad mounted to said belt; and
a drive system coupled to at least said first roller to rotate said first roller
and to cause said belt and said polishing pad to move in a path;
wherein the belt comprises a high-strength polymer.--

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--41. (New) The invention of Claim 40 wherein the belt comprises a
polyethylene terephthalate resin.--

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--42. (New) The invention of Claim 42 wherein said belt is formed of stainless
steel.--

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--43. (New) The invention of Claim 44 wherein said belt is formed of stainless
steel.--